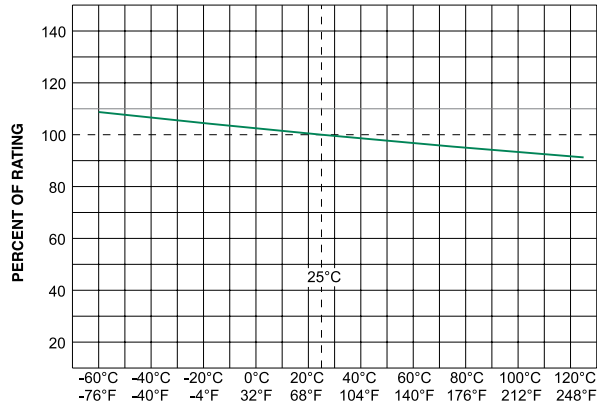
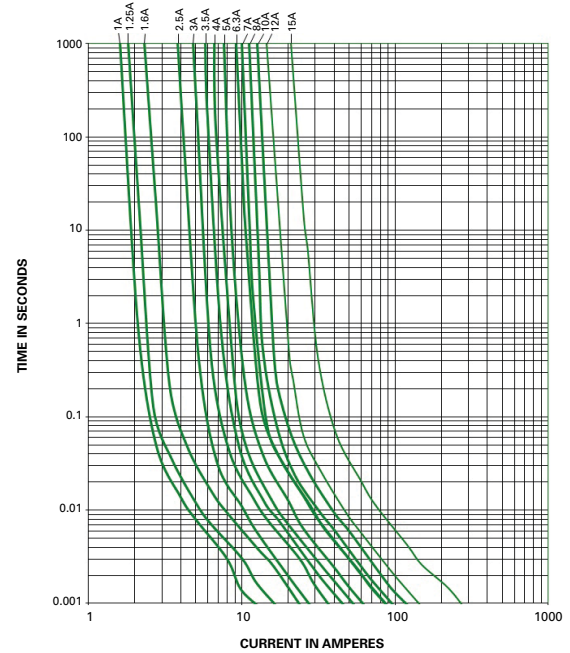


Temperature Derating Curve



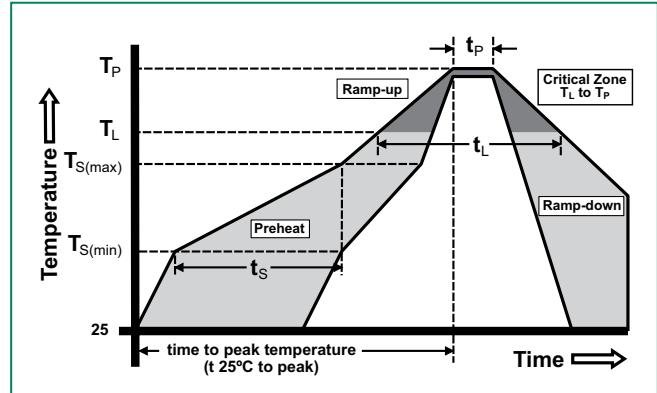
NOTE: Derating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb - free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 seconds
Average Ramp-up Rate (Liquidus Temp (T_L) to peak)		5°C/second max.
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

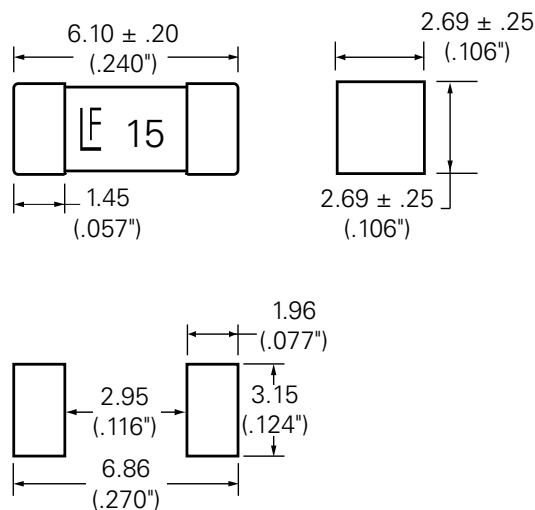


Product Characteristics

Materials	Body: Ceramic Cap: Silver Plated Brass/Sn Dipped Silver Plated Brass/Gold Plated Brass
Product Marking	Body: Brand Logo, Current Rating
Operating Temperature	-55°C to +125°C
Moisture Sensitivity Level	Level 1
Solderability	MIL-STD-202, Method 208
Insulation Resistance (after opening)	IEC 60127-4 (0.1Mohm Min)

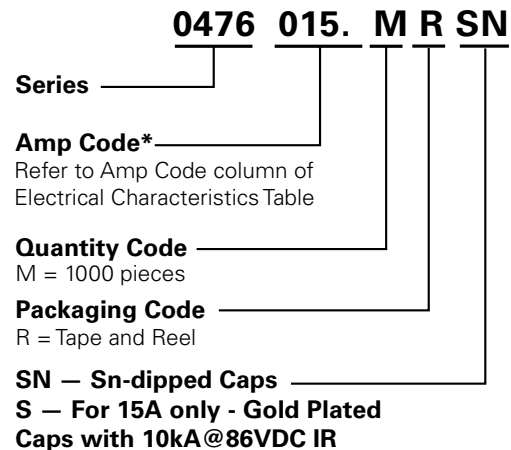
Thermal Shock	MIL-STD-202, Method 107 Test Condition B, 5 cycles, -65°C to 125°C, 15 minutes @ each extreme
Mechanical Shock	MIL-STD-202, Method 213 Test Condition I: De-energized. 100G's peak amplitude, sawtooth wave 6ms duration, 3 cycles XYZ+xyz = 18 shocks
Vibration	MIL-STD-202, Method 201: 0.03" amplitude, 10-55 Hz in 1 min. 2 hrs. each XYZ = 6hrs (10- 55 Hz)
Moisture Resistance	MIL-STD-202, Method 106 10 cycles
Salt Spray	MIL-STD-202, Method 101 Test Condition B (48 hrs)
Resistance to Soldering Heat	MIL-STD-202, Method 210, Test Condition B (10 sec at 260°C)

Dimensions



Recommended Pad Layout

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code	Reel Size
12mm Tape and Reel	EIA-RS-481-2 (IEC 286 part 3)	1000	MR	N/A